

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free): XC6233xxxxGR-G  
Typical Mass: 3 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number	
Silicon chip	0.126	Silicon	42000	7440-21-3	
		- Arsenic	<1	7440-38-2	
Lead pad	0.558	Nickel	185900	7440-02-0	
		Silver	14900	7440-22-4	
		Gold	2700	7440-57-5	
Die attach	0.013	Epoxy Resin	4300	—	
		0.010	Silica	3300	60676-86-0
Bonding wire	0.030	Gold	10100	7440-57-5	
Resin	1.955	Silica	651600	60676-86-0	
		0.045	Silica (crystal)	14900	14808-60-7
		0.111	Epoxy Resin	36900	—
		0.066	Phenol Resin	22100	—
		0.034	Metal hydroxide	11200	—

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."